

## IN THE SPECIFICATION

Please replace the paragraph beginning at page 4, line 24, with:

Fig. 3 shows a carrier 3 in the first embodiment of the invention. The carrier 3 used for receiving a substrate 5 and a die 6 thereon comprises at least one receiving part 32 and a plurality of positioning pins 33. The receiving part 32 contacts with a semiconductor encapsulant package (which comprises the substrate 5 and the die 6 thereon) for receiving the package. The substrate 5 has a side surface. Each of the positioning pins 33 protrudes upwards from an edge of the receiving part 32 for positioning the semiconductor encapsulant package on the carrier 3. Positions and numbers of such positioning pin 33 are unlimited as long as the positioning pins can provide positioning functions. Furthermore, the carrier 3 further comprises a carrier main body 31 used in connection when the carrier 3 receives a plurality of semiconductor encapsulant packages, and the carrier main body 31 comprises constructions that enable the carrier 3 to be applied to machines in manufacture.

Please replace the paragraph beginning at page 5, line 10, with:

The invention is characterized by providing the positioning pin that is at an obtuse angle  $\theta$  to the receiving part; wherein the angle  $\theta$  is larger than  $91^\circ$ . Referring to Fig. 3, in the first embodiment of the invention, a first plane 331 of the positioning pin 33 facing to the substrate 5 is slant; wherein the first plane 331 is at an angle  $\theta$  to the receiving part 32 and the angle  $\theta$  is larger than  $91^\circ$ , for example,  $92^\circ$ ,  $93^\circ$ ,  $95^\circ$ , or  $105^\circ$ . As shown in the figure, the first plane 331 of the positioning pin 33 is only abutted against a lower edge of the side surface of the substrate 5. On the other hand, a second plane 332 of the positioning pin 33 opposite the substrate 5 is vertical and at an angle of about  $90^\circ$  to the receiving part 32.